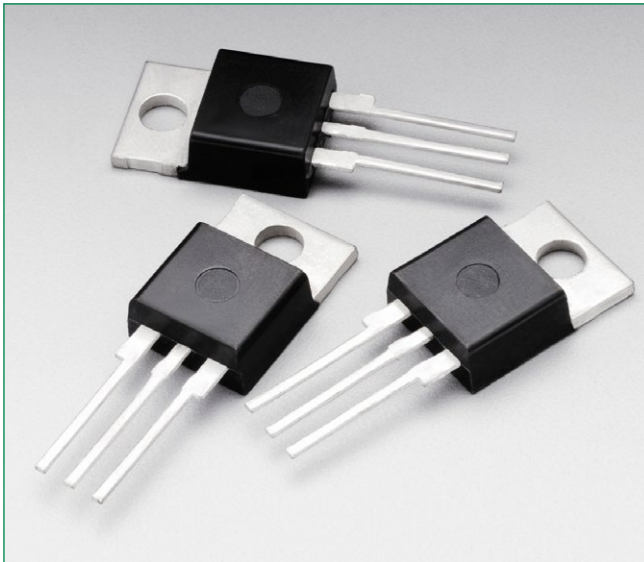


**BTA16-600SW3G, BTA16-800SW3G,**



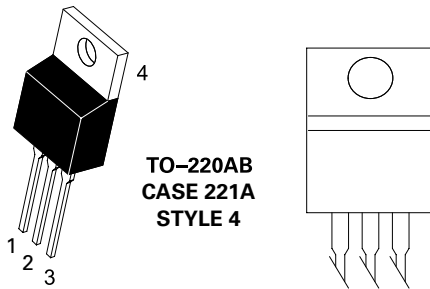
**Description**

Designed for high performance full-wave ac control applications where high noise immunity and high commutating di/dt are required.

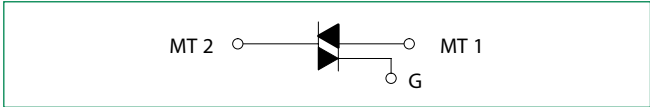
**Features**

- Blocking Voltage to 800 V
- On-State Current Rating of 16 A RMS at 25°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to  $dV/dt$  – 250 V/ $\mu s$  minimum at 110°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating  $di/dt$  – 2 A/ms minimum at 110°C
- Internally Isolated (2500  $V_{RMS}$ )
- These Devices are Pb-Free

**Pin Out**



**Functional Diagram**



**Additional Information**



Datasheet



Resources



Samples

### Maximum Ratings ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (Gate Open, Sine Wave 50 to 60 Hz, $T_J = -40^\circ$ to $125^\circ\text{C}$ )	BTA16-600SW3G BTA16-800SW3G $V_{DRM}^*$ $V_{RRM}$	600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, $T_C = 25^\circ\text{C}$ )	$I_T$ (RMS)	16	A
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_C = 25^\circ\text{C}$ )	$I_{TSM}$	170	A
Circuit Fusing Consideration ( $t = 8.3$ ms)	$I^2t$	120	A <sup>2</sup> sec
Non-Repetitive Surge Peak Off-State Voltage ( $T_J = 25^\circ\text{C}$ , $t = 8.3$ ms)	$V_{DSM}/V_{RSM}$	$V_{DSM}/V_{RSM} + 100$	V
Peak Gate Current ( $T_J = 110^\circ\text{C}$ , $t \leq 20$ $\mu\text{s}$ )	$I_{GM}$	4.0	A
Peak Gate Power (Pulse Width $\leq 20$ $\mu\text{s}$ , $T_C = 80^\circ\text{C}$ )	$P_{GM}$	20	W
Average Gate Power ( $T_J = 125^\circ\text{C}$ )	$P_{G(AV)}$	1.0	W
Operating Junction Temperature Range	$T_J$	-40 to +125	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-40 to +125	$^\circ\text{C}$
RMS Isolation Voltage ( $t = 300$ ms, R.H. $\leq 30\%$ , $T_A = 25^\circ\text{C}$ )	$V_{iso}$	2500	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- $V_{DRM}$  and  $V_{RRM}$  for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

### Thermal Characteristics

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (AC) Junction-to-Ambient	$R_{\theta JC}$ $R_{\theta JA}$	2.13 60	$^\circ\text{C}/\text{W}$
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	$T_L$	260	$^\circ\text{C}$

### Electrical Characteristics - OFF ( $T_J = 25^\circ\text{C}$ unless otherwise noted ; Electricals apply in both directions)

Characteristic	Symbol	Min	Typ	Max	Unit
Peak Repetitive Blocking Current ( $V_D = V_{DRM} = V_{RRM}$ ; Gate Open)	$I_{DRM}^*$ $I_{RRM}$	-	-	0.005	mA
		-	-	2.0	

### Electrical Characteristics - ON ( $T_J = 25^\circ\text{C}$ unless otherwise noted; Electricals apply in both directions)

Characteristic	Symbol	Min	Typ	Max	Unit
Forward On-State Voltage (Note 2) ( $I_{TM} = \pm 22.5$ A Peak)	$V_{TM}$	-	-	1.55	V
Gate Trigger Current (Continuous dc) ( $V_D = 12$ V, $R_L = 30$ $\Omega$ )	MT2(+), G(+)	2.0	-	10	mA
	MT2(+), G(-)	2.0	-	10	
	MT2(-), G(-)	2.0	-	10	
Holding Current ( $V_D = 12$ V, Gate Open, Initiating Current = $\pm 500$ mA)	$I_H$	-	-	20	mA
Latching Current ( $V_D = 12$ V, $I_G = 12$ mA)	MT2(+), G(+)	-	-	25	mA
	MT2(+), G(-)	-	-	30	
	MT2(-), G(-)	-	-	25	
Gate Trigger Voltage ( $V_D = 12$ V, $R_L = 30$ $\Omega$ )	MT2(+), G(+)	0.5	-	1.3	V
	MT2(+), G(-)	0.5	-	1.3	
	MT2(-), G(-)	0.5	-	1.3	
Gate Non-Trigger Voltage ( $T_J = 110^\circ\text{C}$ )	MT2(+), G(+)	0.2	-	-	V
	MT2(+), G(-)	0.2	-	-	
	MT2(-), G(-)	0.2	-	-	

2. Indicates Pulse Test: Pulse Width  $\leq 2.0$  ms, Duty Cycle  $\leq 2\%$ .

### Dynamic Characteristics

Characteristic	Symbol	Min	Typ	Max	Unit
Rate of Change of Commutating Current, See Figure 10. (Gate Open, $T_j = 110^\circ\text{C}$ , No Snubber)	$(di/dt)_c$	2.0	–	–	A/ms
Critical Rate of Rise of On-State Current ( $T_j = 110^\circ\text{C}$ , $f = 120\text{ Hz}$ , $I_g = 20\text{ mA}$ , $t_r \leq 100\text{ ns}$ )	$di/dt$	–	–	50	A/ $\mu\text{s}$
Critical Rate of Rise of Off-State Voltage ( $V_D = 0.66 \times V_{DRM}$ , Exponential Waveform, Gate Open, $T_j = 110^\circ\text{C}$ )	$dV/dt$	250	–	–	V/ $\mu\text{s}$

### Voltage Current Characteristic of SCR

Symbol	Parameter
$V_{DRM}$	Peak Repetitive Forward Off State Voltage
$I_{DRM}$	Peak Forward Blocking Current
$V_{RRM}$	Peak Repetitive Reverse Off State Voltage
$I_{RRM}$	Peak Reverse Blocking Current
$V_{TM}$	Maximum On State Voltage
$I_H$	Holding Current

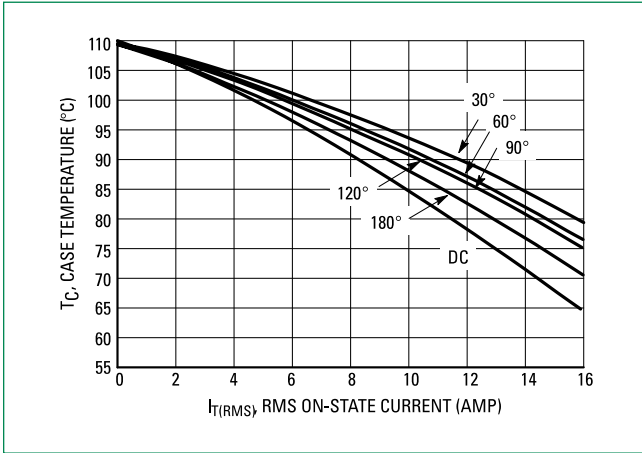


### Quadrant Definitions for a Triac

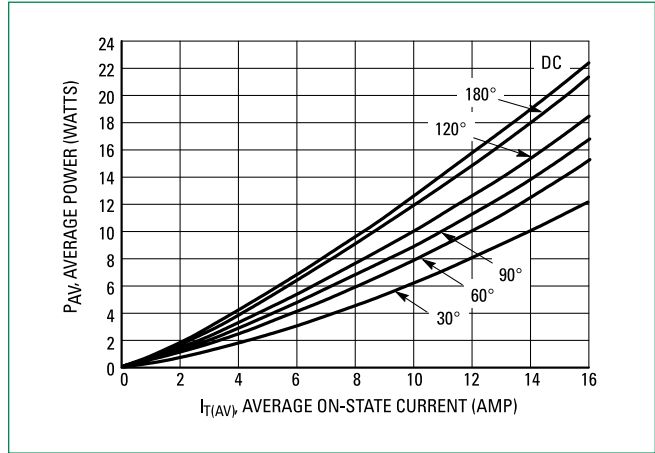


All polarities are referenced to MT1.  
With in-phase signals (using standard AC lines) quadrants I and III are used

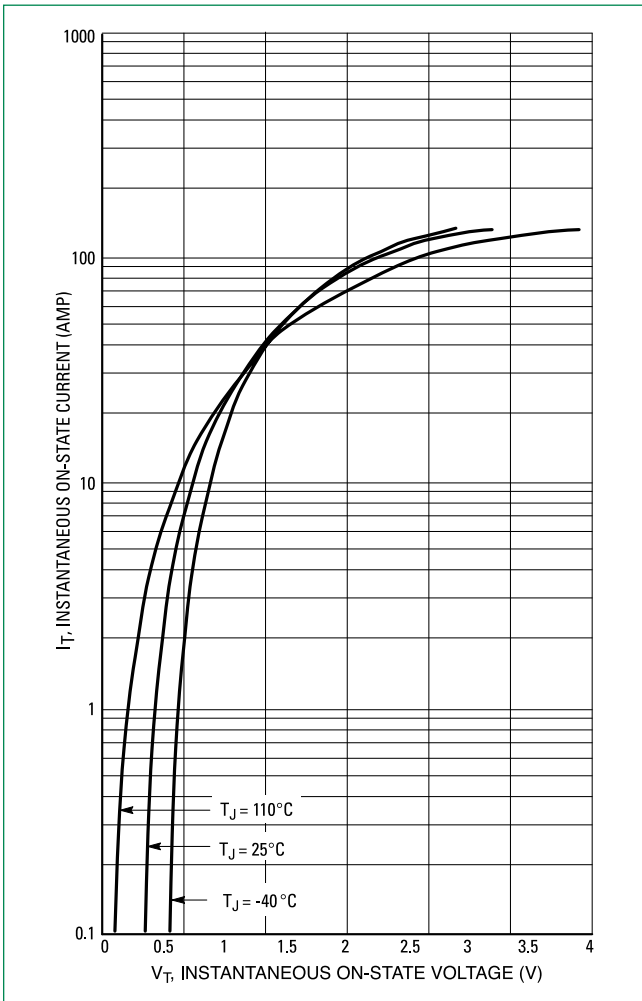
**Figure 1. Typical RMS Current Derating**



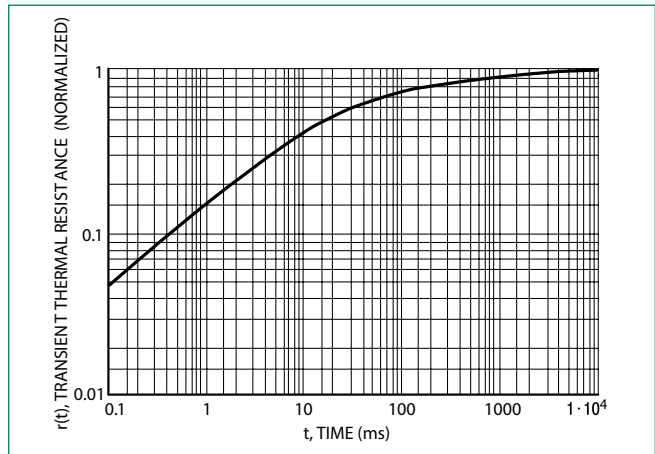
**Figure 2. On-State Power Dissipation**



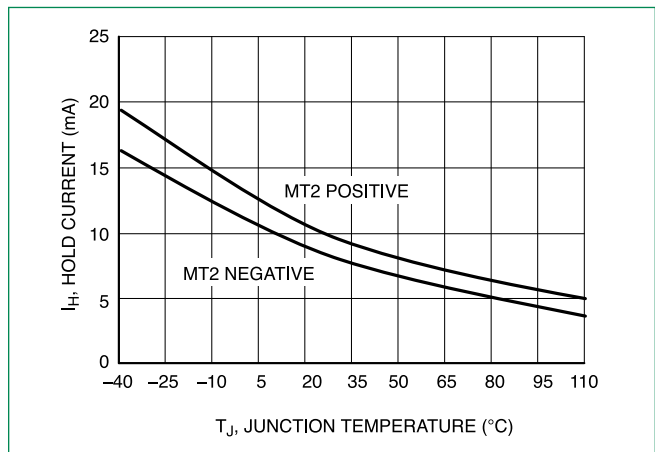
**Figure 3. On-State Characteristics**



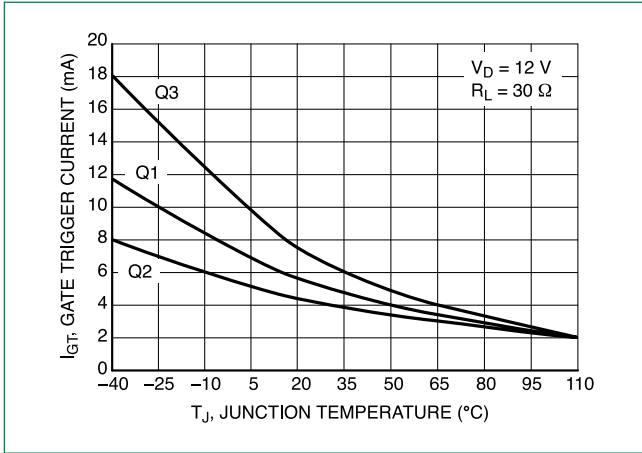
**Figure 4. Thermal Response**



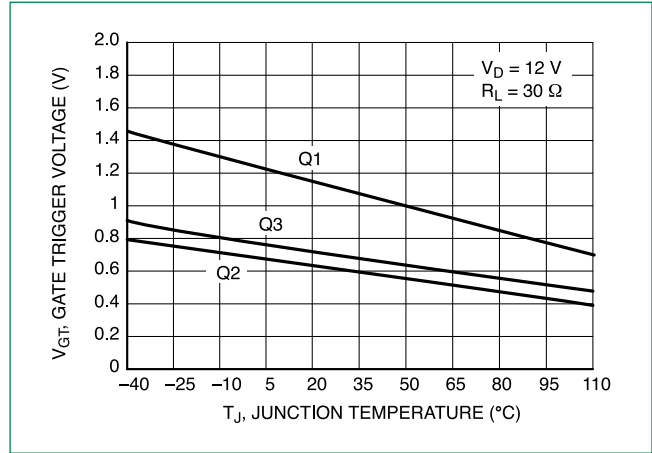
**Figure 5. Hold Current Variation**



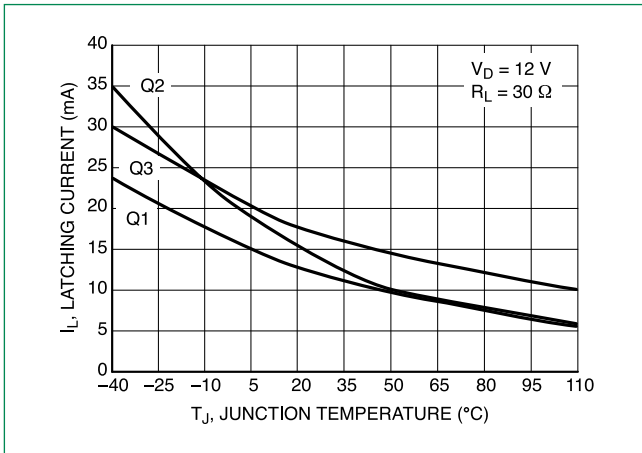
**Figure 6. Gate Trigger Current Variation**



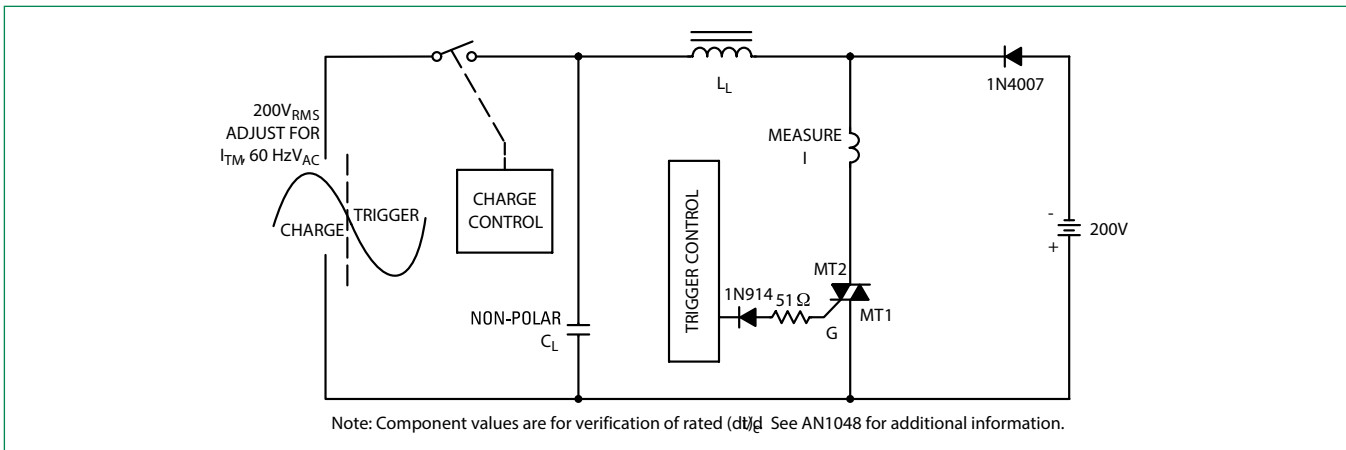
**Figure 7. Gate Trigger Voltage Variation**



**Figure 8. Typical Latching Current Variation**



**Figure 9. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current ( $di/dt$ )**



Note: Component values are for verification of rated ( $di/dt$ )c. See AN1048 for additional information

### Dimensions

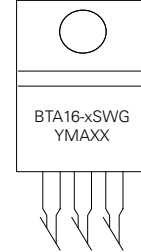


### Part Marking System



**TO-220AB  
CASE 221A  
STYLE 12**

x = 6 or 8  
Y = Year  
M = Month  
A = Assembly Site  
XX = Lot Serial Code  
G = Pb-Free Package



Dim	Inches		Millimeters	
	Min	Max	Min	Max
A	0.590	0.620	14.99	15.75
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
H	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
K	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
N	0.195	0.205	4.95	5.21
Q	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
S	0.045	0.060	1.14	1.52
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	—	1.15	—
Z	—	0.080	—	2.04

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

Pin Assignment	
1	Main Terminal 1
2	Main Terminal 2
3	Gate
4	No Connection

### Ordering Information

Device	Package	Shipping
BTA16-600SW3G	TO-220AB (Pb-Free)	500 Units / Rail
BTA16-800SW3G	TO-220AB (Pb-Free)	500 Units / Rail

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